504281208 03/21/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4327889

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MAGNACHIP SEMICONDUCTOR, LTD.	03/07/2017

RECEIVING PARTY DATA

Name:	HAECHITECH CORPORATION	
Street Address:	525(OFFICETEL RICHIANO), 47, JUNGSIMSANGEOP-RO OCHANG-EUP, CHEONGWON-GU, CHUNGCHEONGBUK-DO	
City:	CHEONGJU-SI	
State/Country:	KOREA, REPUBLIC OF	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15064837

CORRESPONDENCE DATA

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	023117.0024
NAME OF SUBMITTER:	ALICIA M. CHOI
SIGNATURE:	/Alicia M. Choi/
DATE SIGNED:	03/21/2017

Total Attachments: 2

source=Misc20170306_0231170024_20170308LFC_Misc_0231030128_Assignment_ForExecution#page1.tif source=Misc20170306 0231170024 20170308LFC Misc 0231030128 Assignment ForExecution#page2.tif

PATENT REEL: 041657 FRAME: 0110 504281208

ASSIGNMENT

For valuable consideration.

MagnaChip Semiconductor, Ltd., a Republic of Korea corporation having principal executive offices or place of business at 215, Daesin-ro, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 28429, Republic of Korea (hereinafter called "the Assignor"), hereby assign to:

Hacchitech Corporation, a Republic of Korea corporation having principal executive offices or place of business at: 525(officetel richiano), 47, Jungsimsangeop-ro Ochang-eup, Cheongwon-gu, Cheongju-si, Chungcheongbuk-do, Republic of Korea; and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of U.S. Patent Applications:

Application	Filing Date	Title
No.	•	
14/534,547	11-06-2014	SENSING APPARATUS USING GROUPS OF HALL SENSORS
		AND APPARATUS USING THE SENSING APPARATUS
14/287,878	05-27-2014	MAGNETIC SENSOR TEST APPARATUS AND METHOD
14/677,553	04-02-2015	CAPACITOR TYPE HUMIDITY SENSOR
15/085,567	03-30-2016	METHOD FOR CONTROLLING OF HALL DEVICE AND
		MAGNETIC DETECTION APPARATUS USING THE SAME
15/064,837	03-09-2016	PHYSICAL QUANTITY MEASURING APPARATUS AND
***************************************		SIGNAL PROCESSING METHOD THEREOF
15/132,545	04-19-2016	METHOD FOR CALCULATING THE ANGLE OF INCLINATION
		OF MAGNETIC FIELD IN A SENSOR COORDINATION
		SYSTEM
15/219,993	07-26-2016	METHOD AND APPARATUS OF CORRECTING OUTPUT
		VALUE OF GEOMAGNETIC SENSOR

this Assignment includes said applications, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, any reissues, supplemental examinations, and reexaminations, and the right to claim priority based on the filing date of said applications under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and Assignor authorizes the Assignee to apply in all countries in Assignor's name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and

PATENT REEL: 041657 FRAME: 0111 Assignor agrees for itself and its heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, preliminary statements and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

IN TESTIMONY/WITNESS WHEREOF, undersigned Assignor intending to be legally bound, has hereto affixed its signature by its duly authorized representative.

This 7th day of March, 2017

Signature of Representative

Jae Hee Ha

(MagnaChip Semiconductor, Ltd.)

Printed Name of Representative

Legal Team Leader

Title

PATENT REEL: 041657 FRAME: 0112

RECORDED: 03/21/2017